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r the Paperwork Reduction Act of 1995, no persons are required to respond to a collection of information unless it displays a valid OMB control number. 09/716,734 Applicati n Number TRANSMITTAL Nov. 20, 2000 **Filing Date FORM** Chan et al. First Named Inventor Group Art Unit 2826 (to be used for all correspondence after initial filing) A. O. Williams **Examiner Name** 00100.01.0012 Attorney Docket Number Total Number of Pages in This Submission **ENCLOSURES** (check all that apply) After Allowance Communication **Assignment Papers** Fee Transmittal Form (for an Application) to Group Appeal Communication to Board Fee Attached Drawing(s) of Appeals and Interferences Appeal Communication to Group Licensing-related Papers Amendment / Reply (Appeal Notice, Brief, Reply Brief) After Final Proprietary Information Petition to Convert to a Affidavits/declaration(s) **Provisional Application** Status Letter Power of Attorney, Revocation Change of Correspondence Address Other Enclosure(s) (please **Extension of Time Request** identify below): **Terminal Disclaimer** response to Restriction **Express Abandonment Request** Requirement: Postcard Request for Refund Information Disclosure Statement CD, Number of CD(s) Certified Copy of Priority Document(s) Remarks Response to Missing Parts/ Incomplete Application Response to Missing Parts under 37 CFR 1.52 or 1.53 SIGNATURE OF APPLICANT, ATTORNEY, OR AGENT Christopher J. Reckamp Firm Rea. No. 34,414 Individual name Signature February 28, 2002 Date **CERTIFICATE OF MAILING** 

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#### PATENT APPLICATION

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: Chan et al. Serial No. 09/716,734

Filing Date: Nov. 20, 2000 Confirmation No. 7999 Examiner: Alexander O. Williams

Art Group: 2826

Our file no. 00100.01.0012

Docket No. 0100.0100120

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# Title: INTEGRATED CIRCUIT PACKAGE AND METHOD OF FABRICATING SAME

Box Non-Fee Amendment Assistant Commissioner for Patents U.S. Patent and Trademark Office Washington, D.C. 20231

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2/28/02 Date

Rosalie Swanson

#### RESPONSE TO RESTRICTION REQUIREMENT

### In the Claims:

Please amend Claim 21 as follows:

In particular, please substitute the below claim for the indicating pending claim with the same number:

21. (Once Amended) A method for fabricating an integrated circuit, the method comprising the steps of:

providing a first substrate, the first substrate including at least one heat-generating circuit and having a first coefficient of thermal expansion;

providing a second substrate, the second substrate having a second coefficient of thermal expansion that is substantially equal to the first coefficient of thermal expansion;

thermally coupling the first substrate to the second substrate, the second substrate thermally conducts heat generated by the at least one heat-generating circuit away from the at least one heat-generating circuit.